Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75 (1.7 X 2.44 EP)
Lead Count	8
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.21E-02	86.2	862000	35.06	350626
Thermosets	Epoxy resin	Proprietary	8.40E-04	6.0	60000	2.44	24405
Thermosets	Phenol resin	Proprietary	8.40E-04	6.0	60000	2.44	24405
Other inorganic materials	Metal Hydroxide	Proprietary	2.10E-04	1.5	15000	0.61	6101
Other inorganic materials	Carbon black	1333-86-4	4.20E-05	0.3	3000	0.12	1220
Subtotal			1.40 E-02	100.00	1000000	40.68	406758

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.63 E-02	97.50	975000	47.50	474958
Copper & its alloys	Iron	7439-89-6	3.94 E-04	2.35	23500	1.14	11448
Copper & its alloys	Zinc	7440-66-6	2.01 E-05	0.12	1200	0.06	585
Copper & its alloys	Phosphorus	7723-14-0	5.03 E-06	0.03	300	0.01	146
Subtotal			1.68 E-02	100.00	1000000	48.71	487136

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.20 E-05	100.0	1000000	0.12	1220

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.00 E-04	100.0	1000000	2.32	23243

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.00 E-05	100.0	1000000	0.03	291

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.60 E-03	100.0	1000000	7.55	75541

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.55 E-04	77.71	777100	0.45	4516
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	6.22 E-06	3.11	31100	0.02	181
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	6.22 E-06	3.11	31100	0.02	181
Other organic materials	Butyrolactone, gamma-	96-48-0	6.22 E-06	3.11	31100	0.02	181
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	6.22 E-06	3.11	31100	0.02	181
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	6.22 E-06	3.11	31100	0.02	181
Other organic materials	Organosilane	TS ref# 10001	6.22 E-06	3.11	31100	0.02	181
Other inorganic materials	Copper(II) oxide	1317-38-0	6.22 E-06	3.11	31100	0.02	181
Other organic materials	Epoxy resin modifier	TS ref# 10038	1.04 E-06	0.52	5200	0.003	30
Subtotal			2.00 E-04	100.0	1000000	0.58	5811

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.44 E-02**	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.